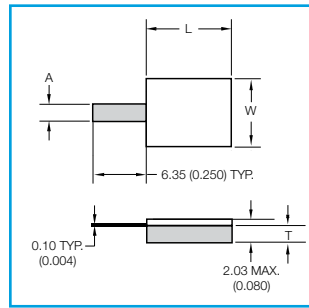


Leaded Chip Terminations

LT1 Style

GENERAL SPECIFICATIONS

- **Nominal Impedance:** 50 Ω
- **Resistive Tolerance:** ±5% standard, ±2% available
- **Operating Temp Range:** -55 to +150°C
- **Temperature Coefficient:** ±150 ppm/°C
- **Resistive Elements:** Tantalum, Thin Film Processed
- **Substrate Material:** Aluminum Nitride
- **Terminals:** Silver over Nickel
- **Lead-Free, RoHS Compliant**
- **Reliability:** MIL-PRF-55342



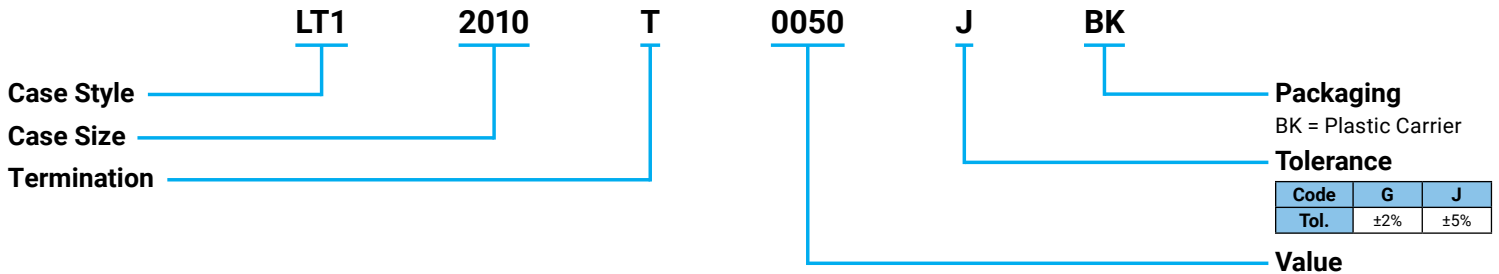
mm

Part Number	W ±.010	L ±.010	T ±.005	A ±.005	Frequency (GHz)	VSWR (Typ.)	Power Max* (Watts)
LT11020T0050J	0.200	0.100	0.025	0.040	DC to 18.0	1.25:1	20W
LT12010T0050J	0.100	0.200	0.040	0.040	DC to 4.0	1.20:1	30W
LT12525T0050J	0.245	0.245	0.040	0.040	DC to 4.0	1.15:1	60W
LT12525T0050J01	0.245	0.245	0.040	0.040	DC to 2.5	1.15:1	100W
LT12525T0050J02	0.245	0.245	0.040	0.040	DC to 4.0	1.20:1	100W
LT12335T0050J	0.350	0.230	0.040	0.040	DC to 4.0	1.15:1	100W
LT13725T0050J	0.250	0.375	0.040	0.040	DC to 4.0	1.20:1	125W
LT13725T0050J01	0.250	0.375	0.040	0.040	DC to 1.1	1.20:1	150W
LT13725T0050J02	0.250	0.375	0.040	0.040	DC to 4.0	1.25:1	150W
LT13725T0050J03	0.250	0.375	0.040	0.120	DC to 4.0	1.25:1	150W
LT13737T0050J	0.370	0.370	0.040	0.040	DC to 2.0	1.25:1	200W
LT13737T0050J01	0.370	0.370	0.040	0.040	DC to 1.0	1.20:1	250W
LT13737T0050J02	0.370	0.370	0.040	0.040	DC to 2.0	1.25:1	250W
LT13737T0050J03	0.370	0.370	0.040	0.120	DC to 2.0	1.25:1	250W

* Test Condition: Chip soldered to a large copper carrier whose surface is at 100°C; maximum rated power applied.

Specification: The resistance of the film shall change no more than <2% during and after a 1000-hr. Burn-in per MIL-PRF-55342.

HOW TO ORDER



POWER DERATING

